

SE120120G
N-Channel Enhancement-Mode MOSFET

Revision: A

General Description

This device used advanced semiconductor technology and design to provide excellent RDS(ON) with low gate charge and low operation voltage. It can be used in wide variety of application

- Excellent package for superior thermal resistance
- Optimized technology for DC/DC converters
- Easy to use and parallel

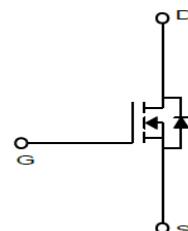
Features

For a single MOSFET

- $V_{DS} = 120V$
- $R_{DS(ON)} = 4.4m\Omega @ V_{GS}=10V$

Pin configurations

See Diagram below



Suffix "A" designates TO-220 package

Absolute Maximum Ratings

Parameter	Symbol	Rating	Units
Drain-Source Voltage	V_{DS}	120	V
Gate-Source Voltage	V_{GS}	± 20	V
Drain Current	Continuous	129	A
	Pulsed	480	
Single Pulse Avalanche Energy	E_{AS}	1000	mJ
Total Power Dissipation @ $T_C=25^\circ C$	P_D	185	W
Operating Junction Temperature Range	T_J	-55 to 175	°C

Thermal Resistance

Symbol	Parameter	Typ	Max	Units
$R_{\theta JC}$	Thermal Resistance Junction to Case($t \leq 10s$)	-	0.8	°C/W

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Electrical Characteristics (TJ=25°C unless otherwise noted)						
Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
OFF CHARACTERISTICS (Note 2)						
BV _{DSS}	Drain-Source Breakdown Voltage	I _D =250μA, V _{GS} =0 V	120			V
I _{DSS}	Drain to Source Leakage Current	V _{DS} =120V, V _{GS} =0V			1	μA
I _{GSS}	Gate-Body Leakage Current	V _{GS} =20V			100	nA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D =250μA	2.5	3.3	4.5	V
R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =10V, I _D =60A	-	4.4	6.1	mΩ
g _{FS}	Forward Transconductance	V _{DS} =10V, I _D =60A	60			S
DYNAMIC PARAMETERS						
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =50V, f=1MHz		5600		pF
C _{oss}	Output Capacitance			641		pF
C _{rss}	Reverse Transfer Capacitance			28		pF
SWITCHING PARAMETERS						
Q _g	Total Gate Charge ²	V _{GS} =10V, V _{DS} =60V, I _D =60A		84.7		nC
Q _{gs}	Gate Source Charge			30.6		nC
Q _{gd}	Gate Drain Charge			18.3		nC
t _{d(on)}	Turn-On Delay Time	V _{GS} =10V, V _{DS} =60, I _D =60A		16		ns
t _{d(off)}	Turn-Off Delay Time			45		ns
t _{d(r)}	Turn-On Rise Time			67		ns
t _{d(f)}	Turn-Off Fall Time			14		ns
Source-Drain Ratings and Characteristics						
I _S	Diode Forward Current				129	A
V _{SD}	Diode Forward Voltage	V _{GS} =0V, I _S =129A			1.2	V
t _{rr}	Reverse Recovery Time	TJ=25°C, IF=IS Di/dt=100A/μs		60		ns
Q _{rr}	Reverse Recovery Charge			140		nC

Typical Characteristics

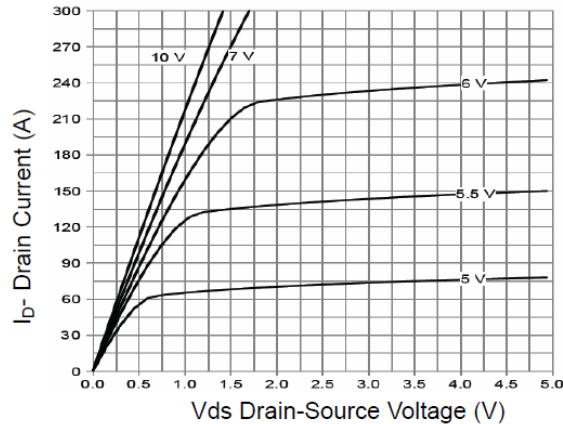


Figure 1 Output Characteristics

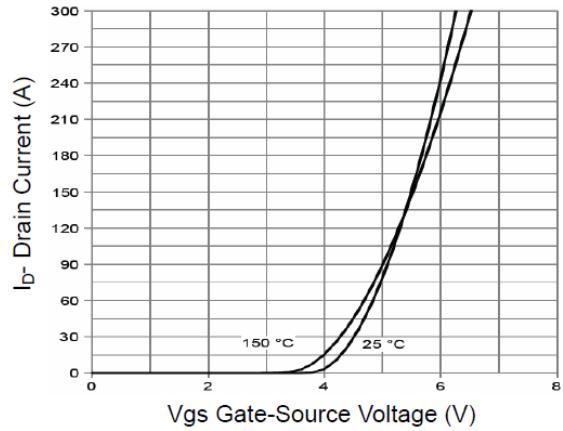


Figure 2 Transfer Characteristics

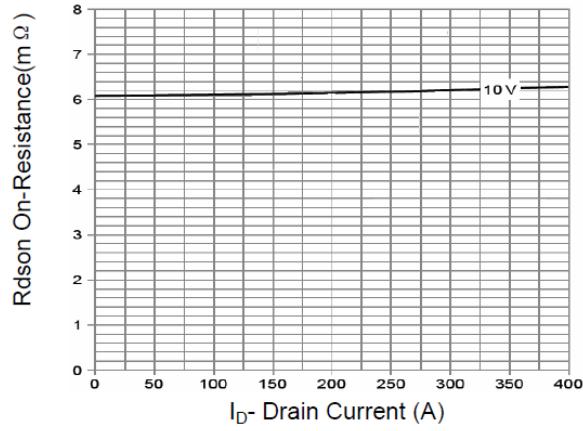


Figure 3 Rdson- Drain Current

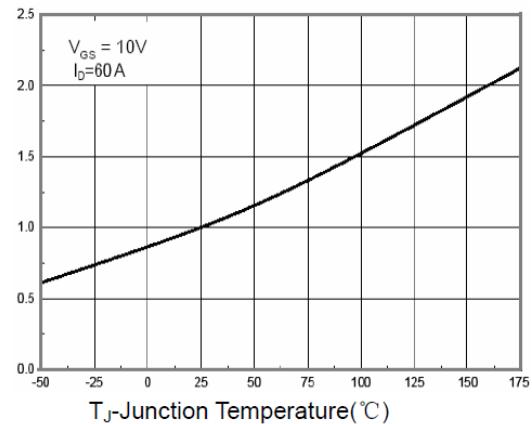


Figure 4 Rdson-Junction Temperature

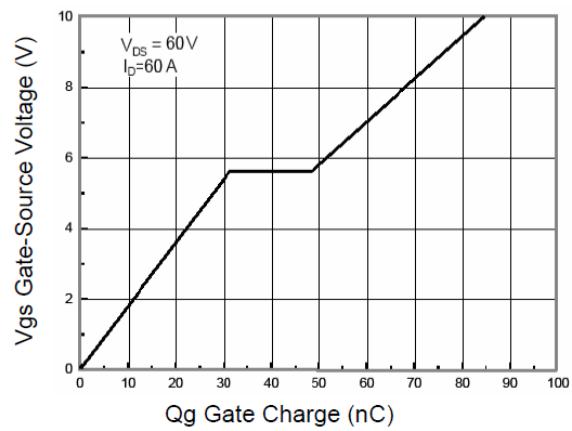


Figure 5 Gate Charge

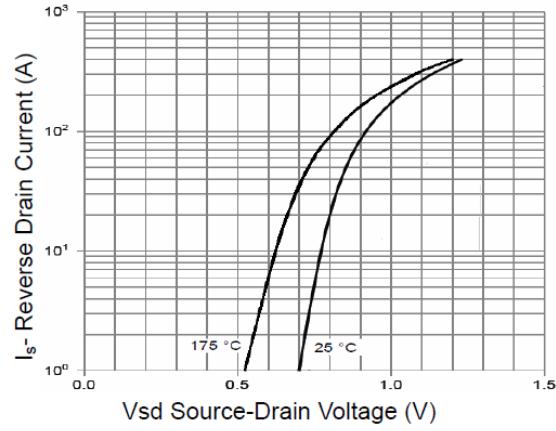


Figure 6 Source- Drain Diode Forward

Typical Characteristics

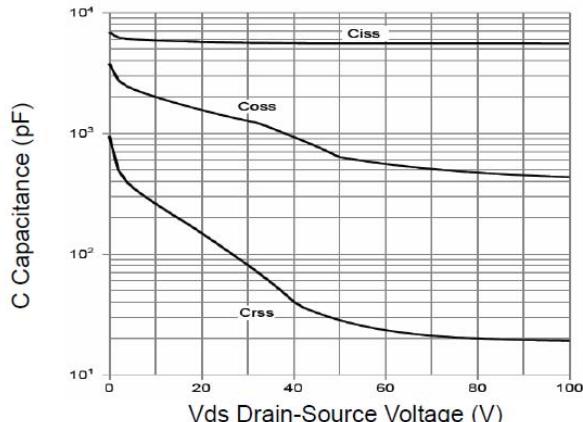


Figure 7 Capacitance vs Vds

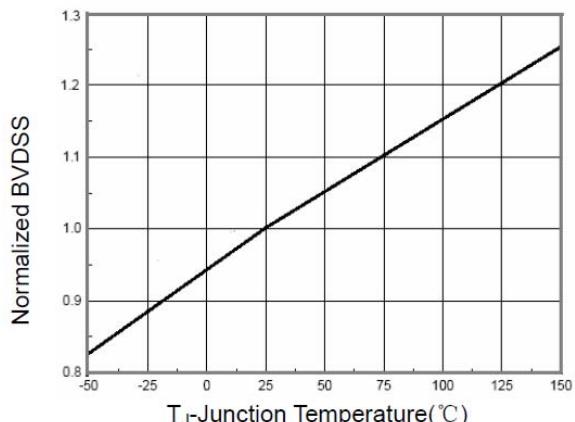


Figure 9 BV_{DSS} vs Junction Temperature

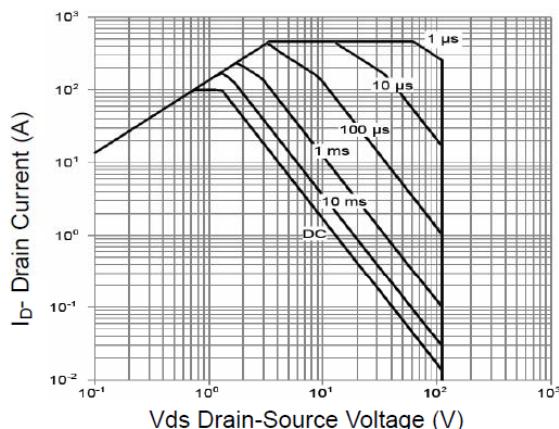


Figure 8 Safe Operation Area

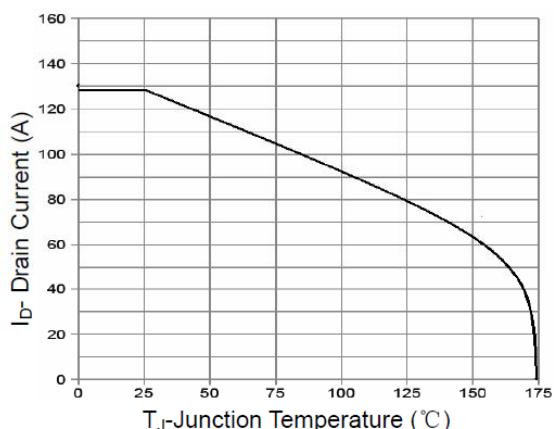


Figure 10 Current De-rating

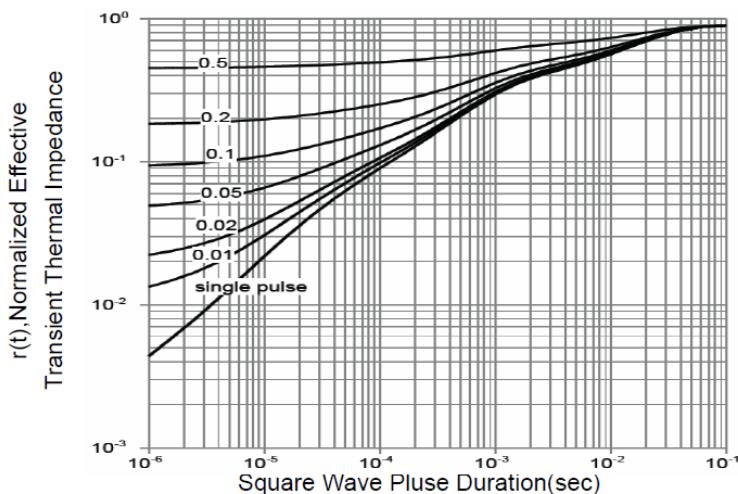
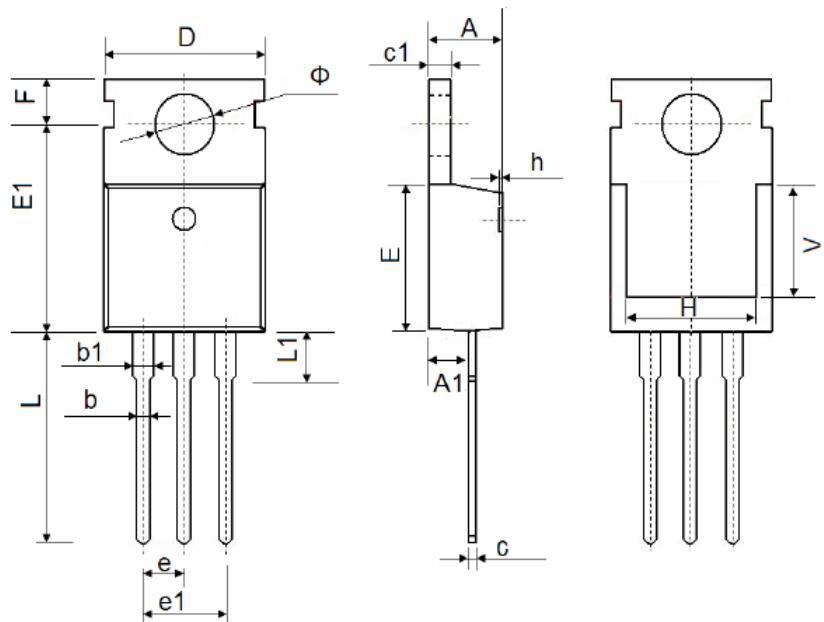


Figure 11 Normalized Maximum Transient Thermal Impedance

Package Outline Dimension

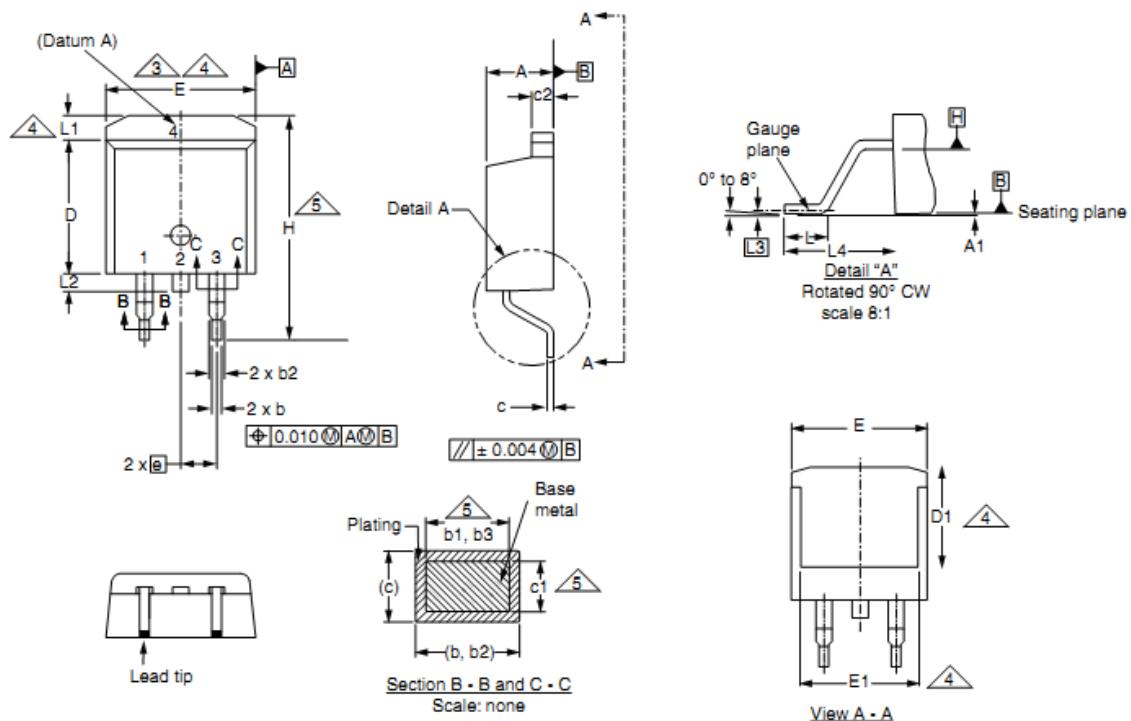
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Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	4.400	4.600	0.173	0.181
A1	2.250	2.550	0.089	0.100
b	0.710	0.910	0.028	0.036
b1	1.170	1.370	0.046	0.054
c	0.330	0.650	0.013	0.026
c1	1.200	1.400	0.047	0.055
D	9.910	10.250	0.390	0.404
E	8.9500	9.750	0.352	0.384
E1	12.650	12.950	0.498	0.510
e	2.540 TYP.		0.100 TYP.	
e1	4.980	5.180	0.196	0.204
F	2.650	2.950	0.104	0.116
H	7.900	8.100	0.311	0.319
h	0.000	0.300	0.000	0.012
L	12.900	13.400	0.508	0.528
L1	2.850	3.250	0.112	0.128
V	7.500 REF.		0.295 REF.	
Φ	3.400	3.800	0.134	0.150

Package Outline Dimension

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DIM.	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	4.06	4.83	0.160	0.190
A1	0.00	0.25	0.000	0.010
b	0.51	0.99	0.020	0.039
b1	0.51	0.89	0.020	0.035
b2	1.14	1.78	0.045	0.070
b3	1.14	1.73	0.045	0.068
c	0.38	0.74	0.015	0.029
c1	0.38	0.58	0.015	0.023
c2	1.14	1.65	0.045	0.065
D	8.38	9.65	0.330	0.380

DIM.	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
D1	6.86	-	0.270	-
E	9.65	10.67	0.380	0.420
E1	6.22	-	0.245	-
e	2.54 BSC		0.100 BSC	
H	14.61	15.88	0.575	0.625
L	1.78	2.79	0.070	0.110
L1	-	1.65	-	0.066
L2	-	1.78	-	0.070
L3	0.25 BSC		0.010 BSC	
L4	4.78	5.28	0.188	0.208

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